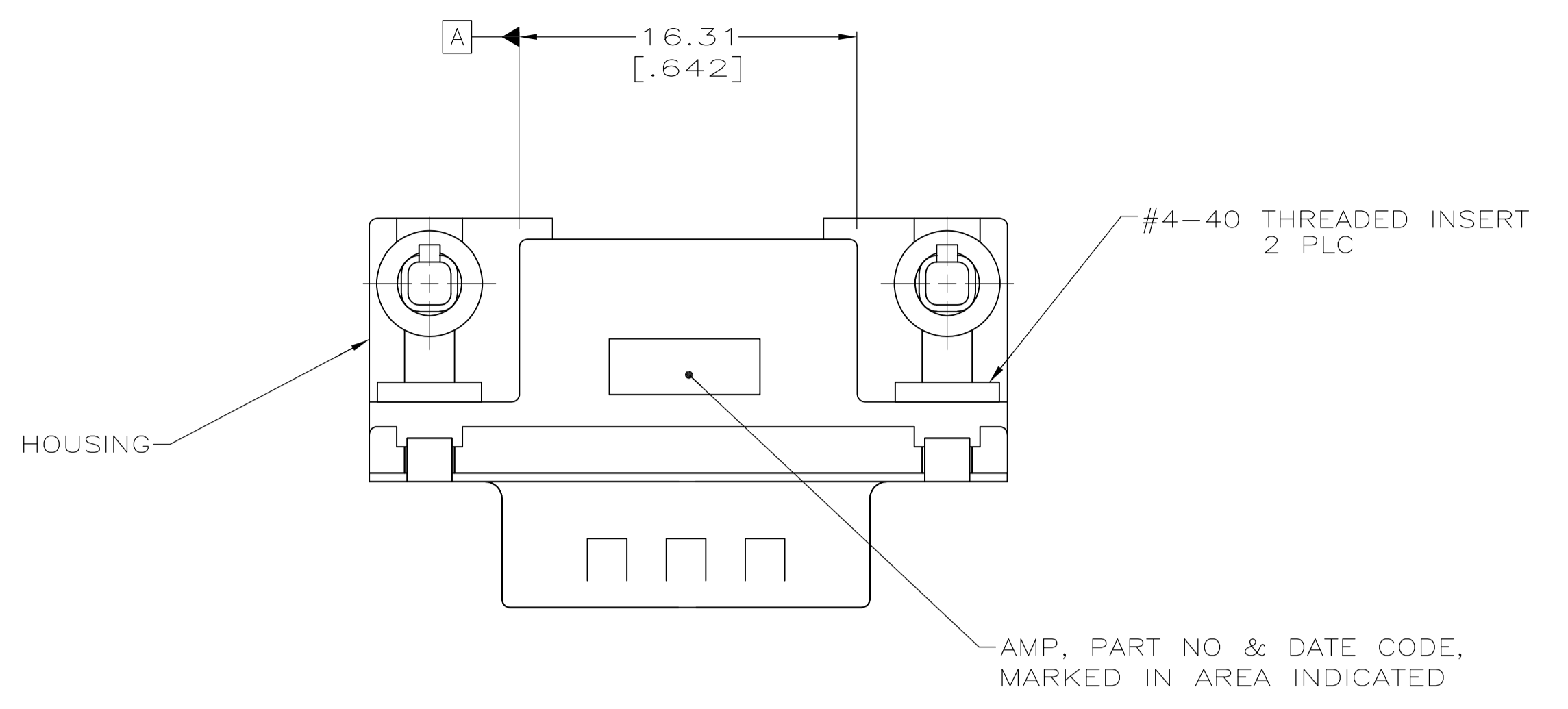


LOC		DIST		REVISIONS			
GP	00	P	LTR	DESCRIPTION	DATE	DMN	APVD
E				REVISED PER ECO-12-022391	02JAN2013	CJV	SLB



1 HOUSING: NYLON, THERMOPLASTIC, UL 94VO RATED, BLACK.
SHELL: CARBON STEEL.
PIN CONTACTS: BRASS
EYELETS: BRASS.
THREADED INSERTS: ZINC.
BOARDLOCKS: COPPER ALLOY.

2 PIN CONTACTS: 0.76µm[.000030] MIN GOLD PLATE ON THE MATING SURFACES, 2.54µm[.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27µm[.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT
-OR-
GOLD FLASH OVER PALLADIUM-NICKEL PLATE, 0.76µm[.000030] MIN TOTAL ON THE MATING SURFACES, 2.54µm[.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27µm[.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT.
EYELETS: 2.54µm[.000100] MIN TIN-LEAD OR TIN OVER COPPER FLASH.
SHELL: 2.54µm[.000100] MIN TIN OVER 1.27µm[.000050] MIN COPPER.
THREADED INSERTS: CLEAR CHROMATE.
BOARDLOCKS: 3.81µm[.000150] MIN TIN OVER 1.27µm[.000050] MIN NICKEL.

3 PIN CONTACTS: GOLD FLASH ON THE MATING SURFACES, 2.54µm[.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27µm[.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT.
EYELETS: 2.54µm[.000100] MIN TIN-LEAD OR TIN OVER COPPER FLASH.
SHELL: 2.54µm[.000100] MIN TIN OVER 1.27µm[.000050] MIN COPPER.
THREADED INSERTS: CLEAR CHROMATE.
BOARDLOCKS: 3.81µm[.000150] MIN TIN-LEAD OVER 1.27µm[.000050] MIN NICKEL.

4 DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.

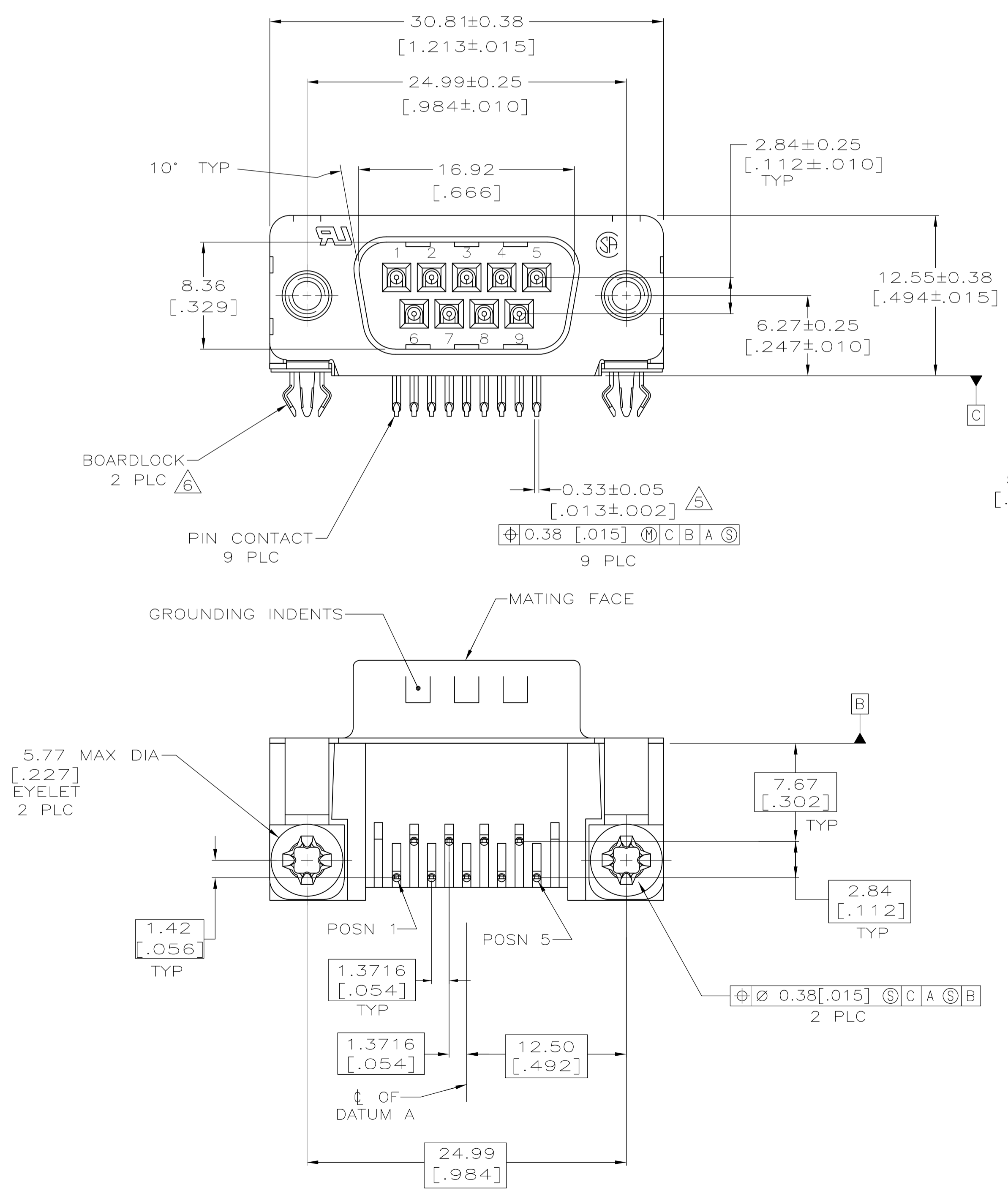
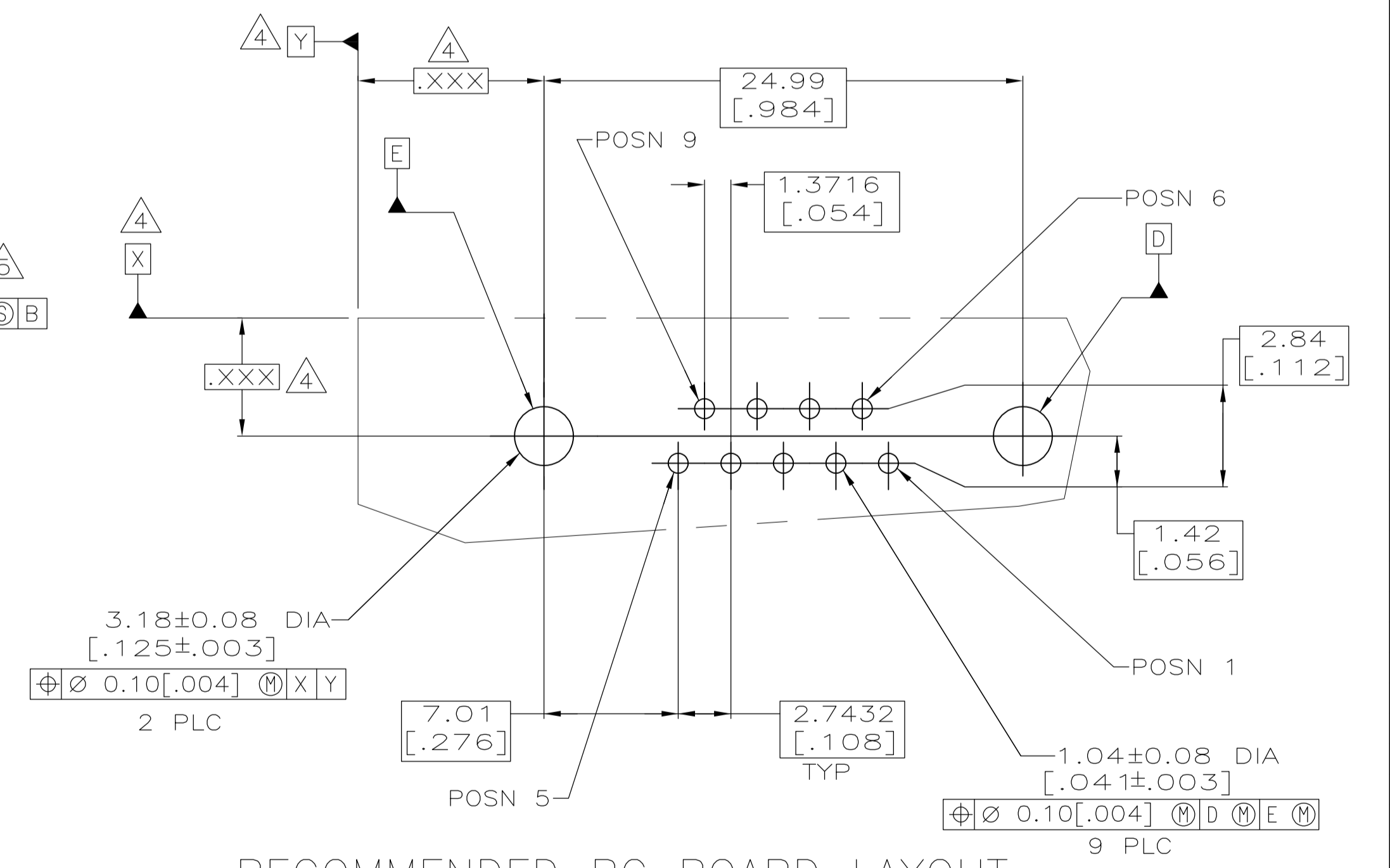
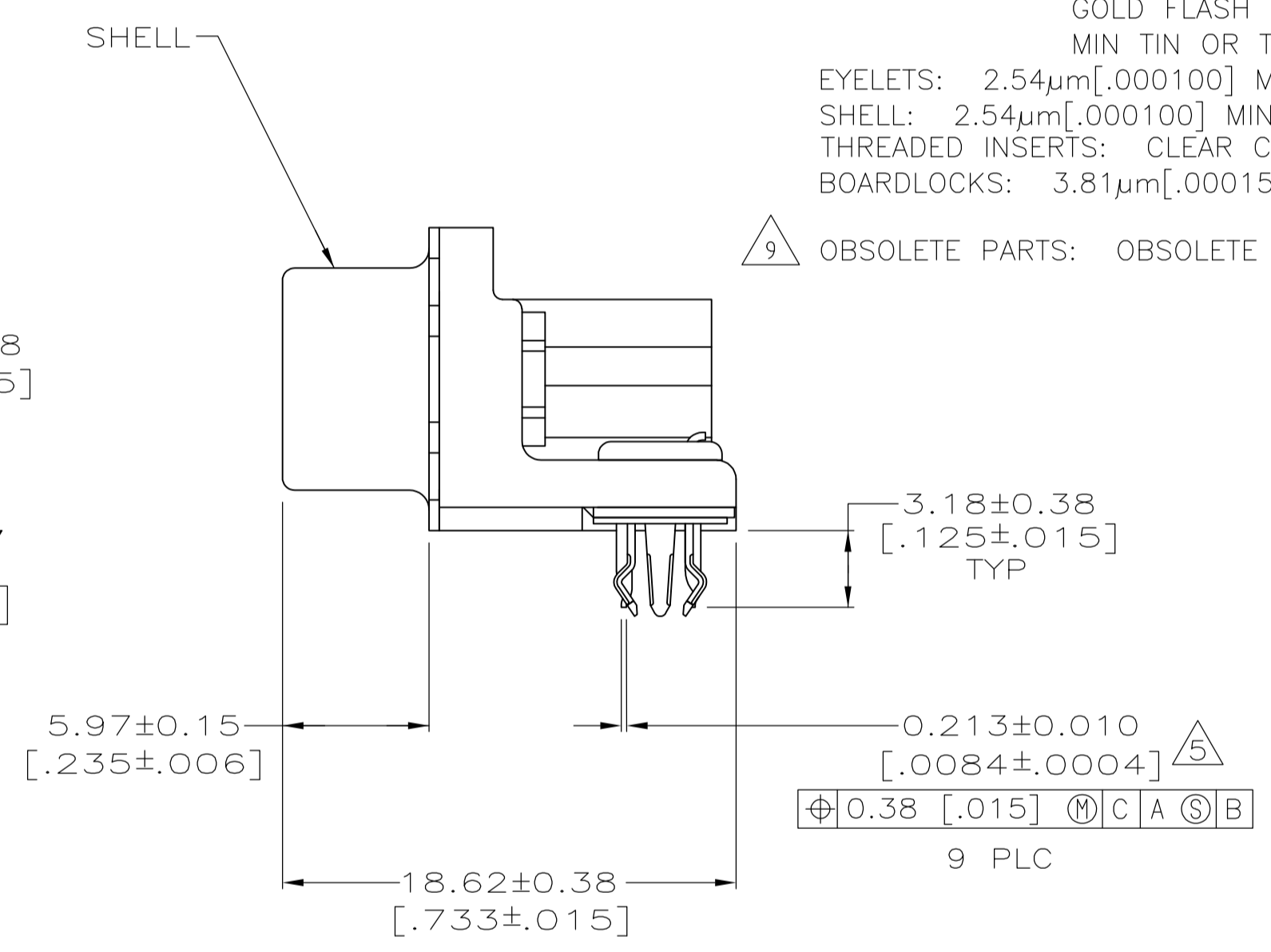
5 POSITION TOLERANCE APPLIES AT CONTACT TIP.

6 BOARDLOCKS WILL ACCEPT .062 MAX PRINTED CIRCUIT BOARD THICKNESS.

7 COMPATIBLE WITH TYPICAL HIGH TEMPERATURE SOLDERING APPLICATIONS TO A MAXIMUM OF 225°C FOR A MAXIMUM DURATION OF 90 SECONDS. TEMPERATURE TO BE MEASURED ON CONNECTOR SURFACE.

8 PIN CONTACTS: 0.76µm[.000030] MIN GOLD PLATE ON THE MATING SURFACES, 2.54µm[.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27µm[.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT
-OR-
GOLD FLASH OVER PALLADIUM-NICKEL PLATE, 0.76µm[.000030] MIN TOTAL ON THE MATING SURFACES, 2.54µm[.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27µm[.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT.
EYELETS: 2.54µm[.000100] MIN TIN-LEAD OR TIN OVER COPPER FLASH.
SHELL: 2.54µm[.000100] MIN TIN OVER 1.27µm[.000050] MIN COPPER.
THREADED INSERTS: CLEAR CHROMATE.
BOARDLOCKS: 3.81µm[.000150] MIN TIN OVER 1.27µm[.000050] MIN NICKEL.

9 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI.



9 OBSOLETE	8	6-788792-7
SUP BY 5788792-2	3	788792-2
	2	788792-1
FINISH		PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009		DIN D.BROCKWAY 23 FEB 00		STE TE Connectivity	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME	
Ø		±		J.KOPPENHEFFER	
H		±		J.KOPPENHEFFER	
L		±		NAME	
R		±		PRODUCT SPEC	
S		±		108-40025	
T		±		APPLICATION SPEC	
V		±		114-40010	
W		±		SIZE	
X		±		CAGE CODE	
Y		±		DRAWING NO	
Z		±		RESTRICTED TO	
Ø		±		A1 00779 C=788792	
H		±		WEIGHT	
L		±		CUSTOMER DRAWING	
R		±		SCALE	
S		±		4:1	
T		±		SHEET	
V		±		1 of 1	
W		±		REV	
X		±		E	
Y		±			
Z		±			

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[788792-1](#)